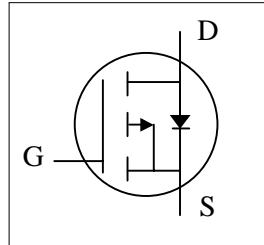




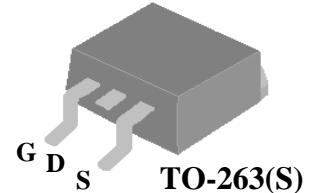
- ▼ Lower On-resistance
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant



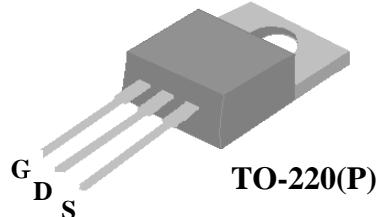
$BV_{DSS}$	-40V
$R_{DS(ON)}$	13.5mΩ
$I_D$	-65A

## Description

The Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.



The TO-263 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters. The through-hole version (AP6679GP) are available for low-profile applications.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	±25	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	-65	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	-41	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	-260	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	89	W
	Linear Derating Factor	0.71	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-c}$	Thermal Resistance Junction-case	Max.	1.4 °C/W
$R_{thj-a}$	Thermal Resistance Junction-ambient	Max.	62 °C/W



## Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-40	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	-	-0.02	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-28\text{A}$	-	-	13.5	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-20\text{A}$	-	-	20	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-0.8	-	-2.5	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_{\text{D}}=-24\text{A}$	-	24	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current ( $T_j=25^\circ\text{C}$ )	$V_{\text{DS}}=-40\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
	Drain-Source Leakage Current ( $T_j=150^\circ\text{C}$ )	$V_{\text{DS}}=-32\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	-25	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}= \pm 25$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=-16\text{A}$	-	43	70	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=-32\text{V}$	-	7	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=-4.5\text{V}$	-	26	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=-20\text{V}$	-	11	-	ns
$t_r$	Rise Time	$I_{\text{D}}=-16\text{A}$	-	40	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_G=3.3\Omega$ , $V_{\text{GS}}=-10\text{V}$	-	50	-	ns
$t_f$	Fall Time	$R_D=0.8\Omega$	-	80	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	2870	4590	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=-25\text{V}$	-	960	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	740	-	pF
$R_g$	Gate Resistance	f=1.0MHz	-	2.5	3.75	$\Omega$

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_{\text{S}}=-20\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	-1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_{\text{S}}=-16\text{A}$ , $V_{\text{GS}}=0\text{V}$ ,	-	37	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$dI/dt=-100\text{A}/\mu\text{s}$	-	42	-	nC

## Notes:

- 1.Pulse width limited by safe operating area.
- 2.Pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .

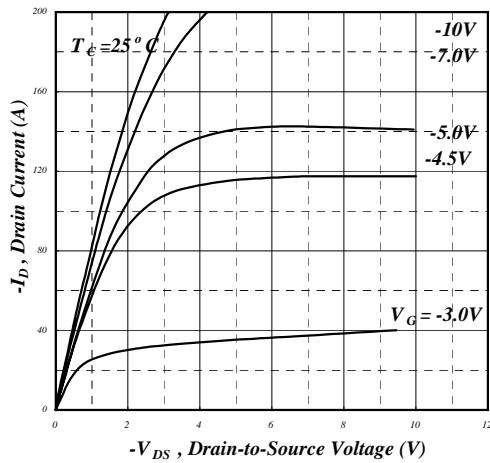


Fig 1. Typical Output Characteristics

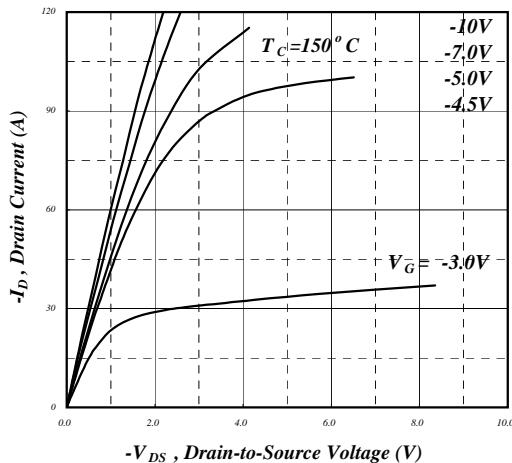


Fig 2. Typical Output Characteristics

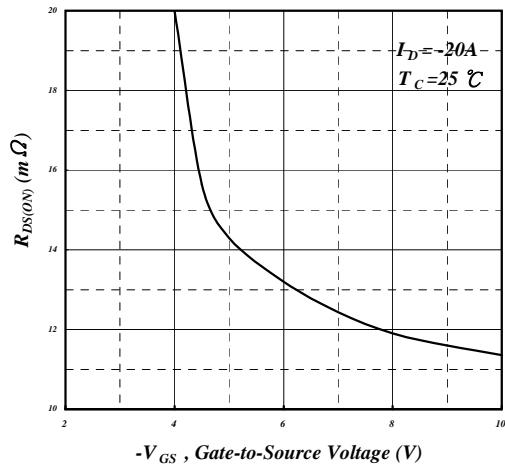


Fig 3. On-Resistance v.s. Gate Voltage

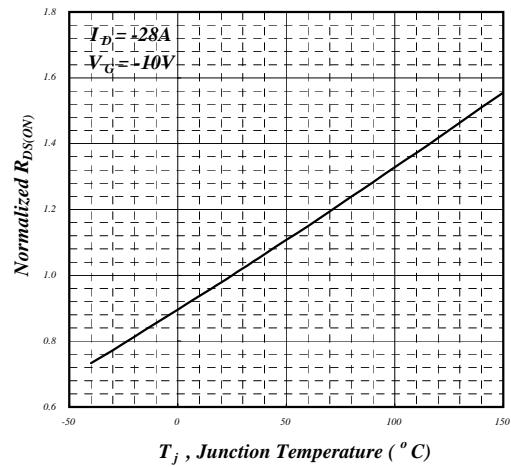


Fig 4. Normalized On-Resistance v.s. Junction Temperature

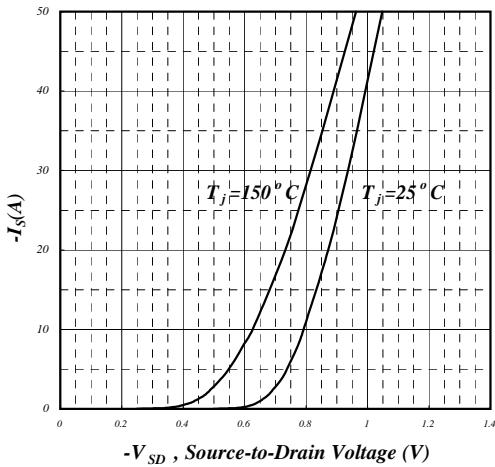


Fig 5. Forward Characteristic of Reverse Diode

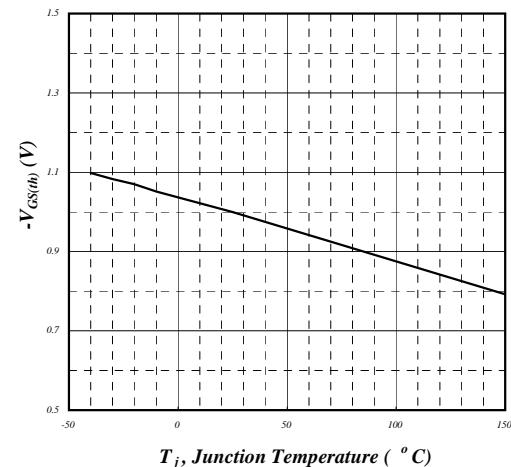
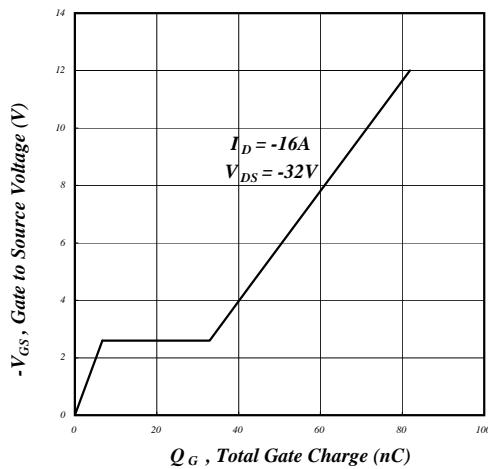
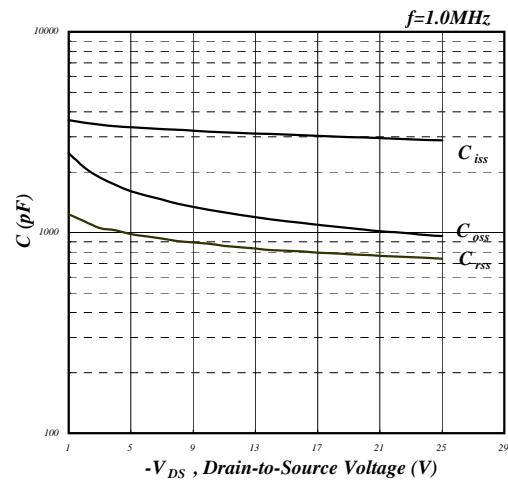


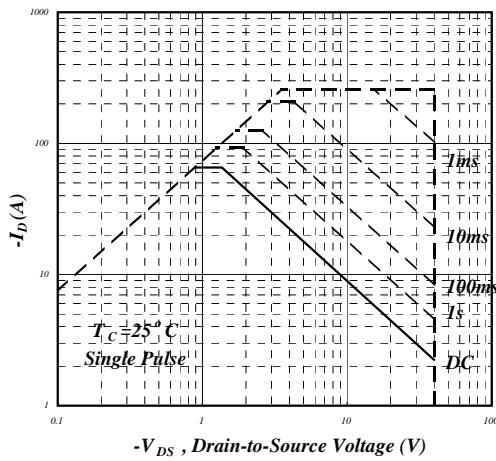
Fig 6. Gate Threshold Voltage v.s. Junction Temperature



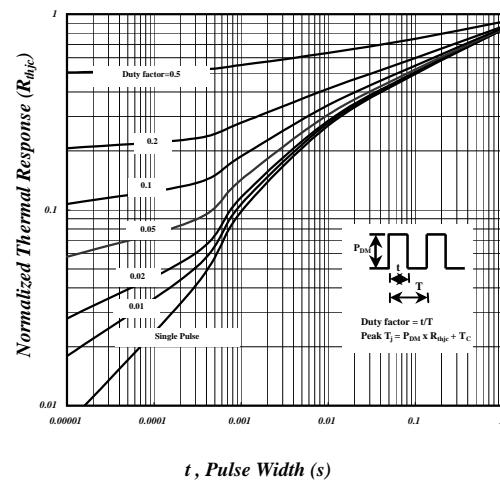
**Fig 7. Gate Charge Characteristics**



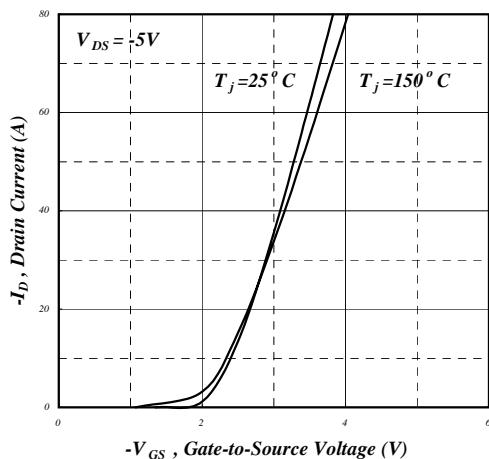
**Fig 8. Typical Capacitance Characteristics**



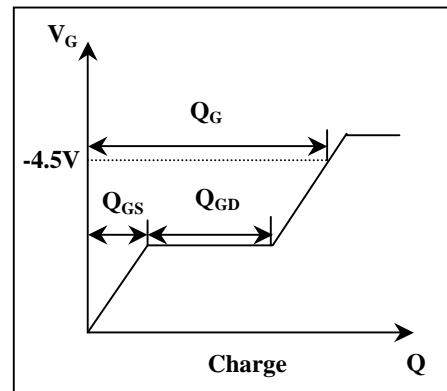
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



**Fig 11. Transfer Characteristics**



**Fig 12. Gate Charge Waveform**